

T0 Package Test socket, Stamping contact type GU16 series Size 16x27.9mm / 0.63x1.10"

T0-252/D-PAK
Burn-in Test
Kelvin Contact (option)
Cost competitive

Specifications
Contact resistance : 50mΩ max
Current rating : 1.5A *
Withstanding Voltage : DC500Vrms 1min
Insulation Resistance : 500MΩmin at DC500V
Operating temperature : -40℃~+175℃

* Please contact us for the high current type.

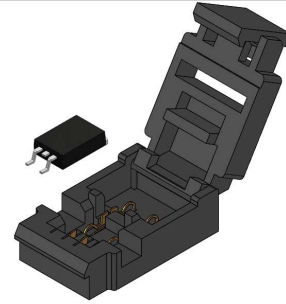
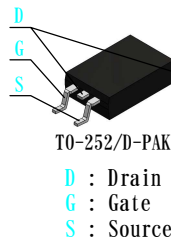
T0-252/D-PAK Package Test Socket

How to order

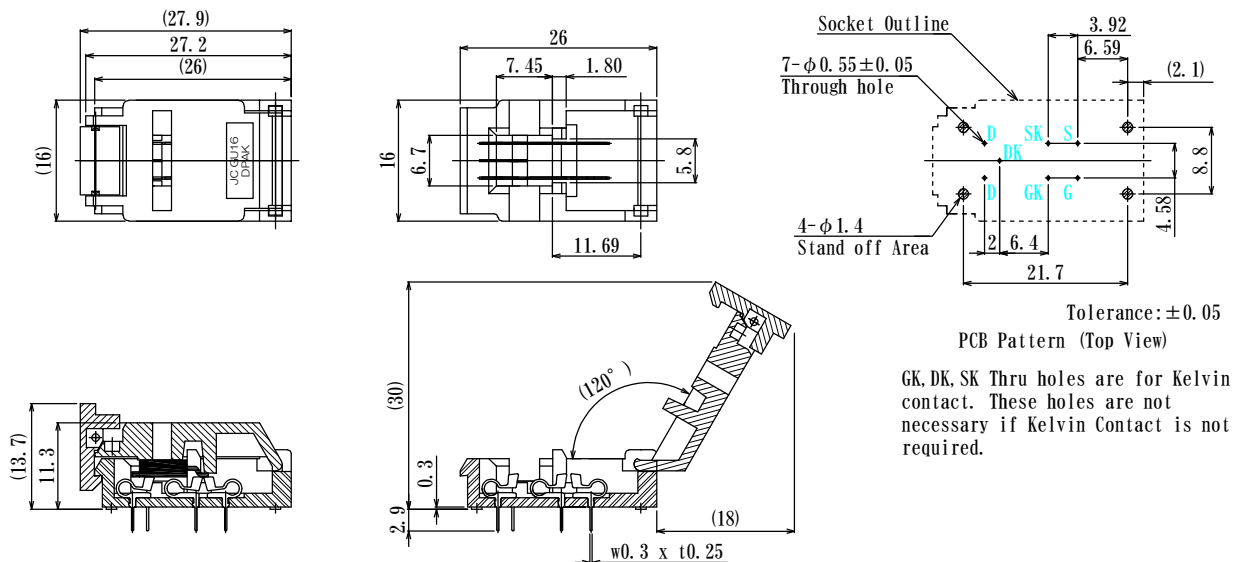
GU16 - T0252 - K - 745X67

T0-252 D-PAK Package Device Guide Size

N : No Kelvin Contact
K : With Kelvin Contact



Actual Size



Acceptable Device Table

			Typical Dimension	
NTD5862N (ON Semiconductor)	RD3U080AAFRA (ROHM)	IXTY14N60X2 (IXYS)	6.49	2.29
			7.22	9.98
			0.75	0.5
SUD50N06-09L (Vishay)	Generally, T0-252/D-PAK package size is specified. However, the size depends on the semiconductor manufacturers and devices. If you send us your device in advance, we can properly confirm its adoption.			

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T0 Package Test socket, Stamping contact type
GU16 series
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T0-263/D2-PAK
Burn-in Test
Kelvin Contact (option)
Cost competitive

Specifications
Contact resistance : 50mΩ max
Current rating : 1.5A *
Withstanding Voltage : DC500Vrms 1min
Insulation Resistance : 500MΩmin at DC500V
Operating temperature : -40℃~+175℃

* Please contact us for the high current type.

T0-263/D2-PAK Package Test Socket

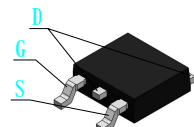
How to order

GU16 - T0263 - K - S1045X103

T0-263
D2-PAK
Package

S1045X103 :
Device Guide Size, 10.3x10.45mm
L1090X103 :
Device Guide Size, 10.3x10.9mm

N : No Kelvin Contact
K : With Kelvin Contact

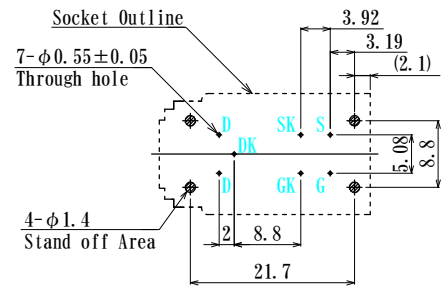
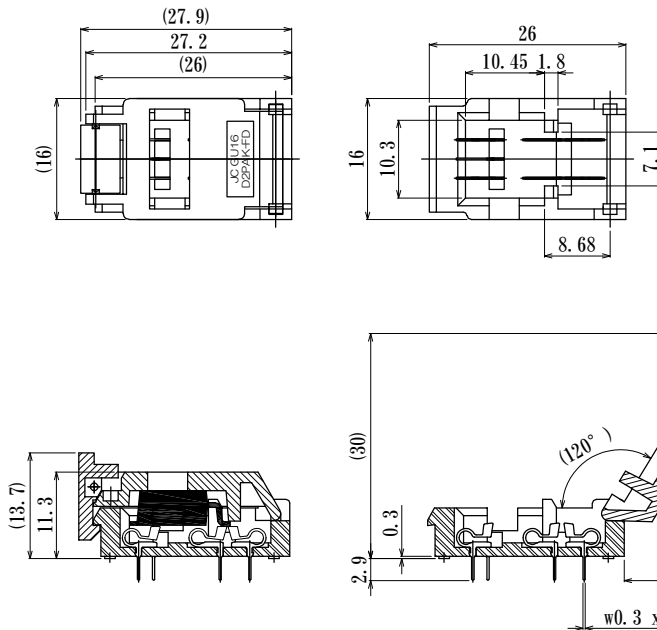


T0-263/D2-PAK (FD)

D : Drain
G : Gate
S : Source



● Actual Size (Small Device type)



Tolerance: ±0.05

PCB Pattern (Top View)

GK, DK, SK Thru holes are for Kelvin contact.
These holes are not necessary if Kelvin Contact is not required.

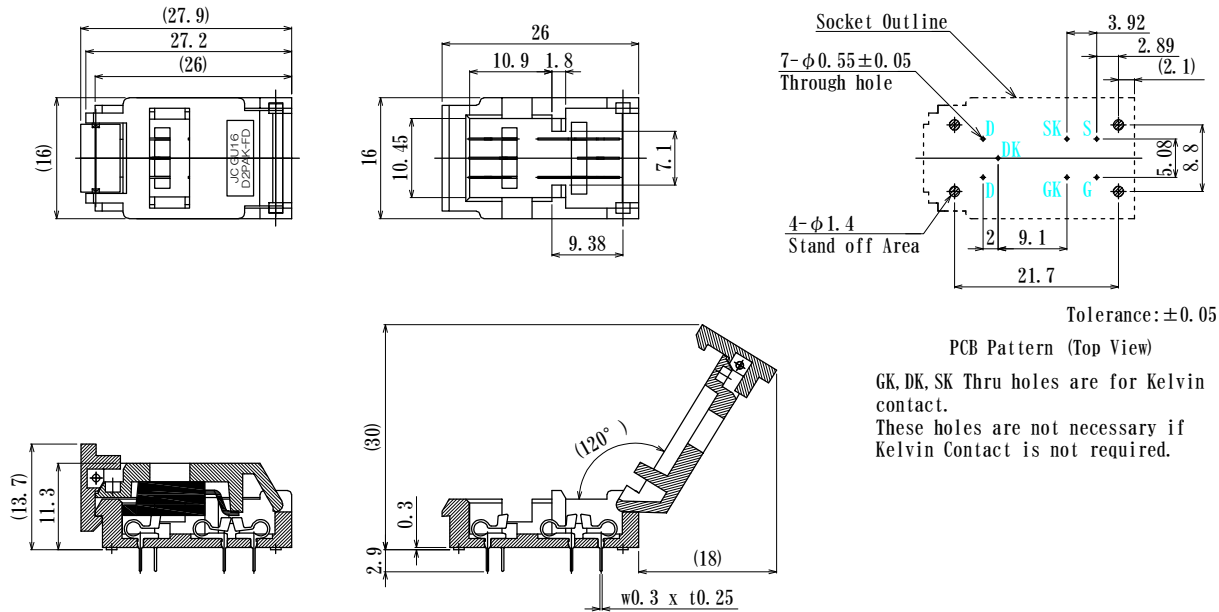
● Acceptable Device Table

Typical Dimension	

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● Actual Size (Large Device type)



● Acceptable Device Table

				Typical Dimension
<p>IRF5305STRLPBF (Infineon)</p>	<p>VS-10TTS08S-M3 (Vishay)</p>	<p>FDB28N30 (ON Semiconductor)</p>	<p>SK107114 (Sanken)</p>	
<p>C3D06060G (CREE)</p>				

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